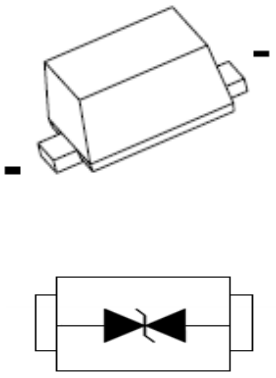
FEATURES

- ✧ Small body outline dimensions: 0.063″ × 0.032″ (1.6×0.8 mm)
- ✧ Protects one bi-directional I/O line
- ✧ Low clamping voltage
- ✧ Working voltage: 12V
- ✧ Low leakage current
- ✧ RoHS compliant

SOD-523



Pin Configuration

MAIN APPLICATIONS

- ✧ LED light bar
- ✧ Cell phone handsets and accessories
- ✧ Microprocessor based equipment
- ✧ Personal digital assistants (PDA's)
- ✧ Notebooks, desktops, and servers
- ✧ Portable instrumentation
- ✧ Peripherals
- ✧ Digital cameras

PROTECTION SOLUTION TO MEET

- ✧ IEC61000-4-2 (ESD) ±20kV (air), ±20kV (contact)
- ✧ IEC61000-4-4 (EFT) 40A (5/50ns)
- ✧ IEC61000-4-5 (Lightning) 5A (8/20μs)

MECHANICAL CHARACTERISTICS

- ✧ SOD-523 package
- ✧ Molding compound flammability rating: UL 94V-0
- ✧ Weight 0.5 milligrams (approximate)
- ✧ Quantity per reel: 5,000pcs
- ✧ Lead finish: lead free

MARKING CODE



ORDERING INFORMATION

PART No.	PACKAGE TYPE	QUANTITY(PCS) REEL	DESCIPTION
TESDB12D5	SOD-523	5,000	7 inch reel pack

ABSOLUTE MAXIMUM RATINGS (T_A=25℃, RH=45%-75%, unless otherwise noted)

Parameter	Symbol	Value	Unit
Peak pulse power dissipation on 8/20μs waveform	P_{PP}	100	W
ESD per IEC 61000-4-2 (Air) ESD per IEC 61000-4-2 (Contact)	V_{ESD}	+/- 20 +/- 20	kV
Lead soldering temperature	T_L	260 (10 sec.)	℃
Operating junction temperature range	T_J	-55 to +125	℃
Storage temperature range	T_{STG}	-55 to +150	℃

ELECTRICAL CHARACTERISTICS (T_A=25℃)

Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Reverse working voltage	V_{RWM}				12	V
Reverse breakdown voltage	V_{BR}	I_T=1mA	13.3			V
Reverse leakage current	I_R	V_{RWM}=12V			0.1	μA
Clamping voltage	V_C	I_{PP}=5A, t_P=8/20μs		22	26	V
Junction capacitance	C_J	V_{RWM}=0V, f=1MHz		10	20	pF

RATINGS AND V-I CHARACTERISTICS CURVES (T_A=25℃, unless otherwise noted)

FIG.1:V- I curve characteristics (Bi-directional)

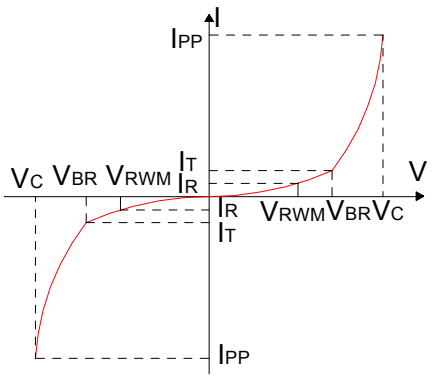


FIG.2: Pulse waveform (8/20μs)

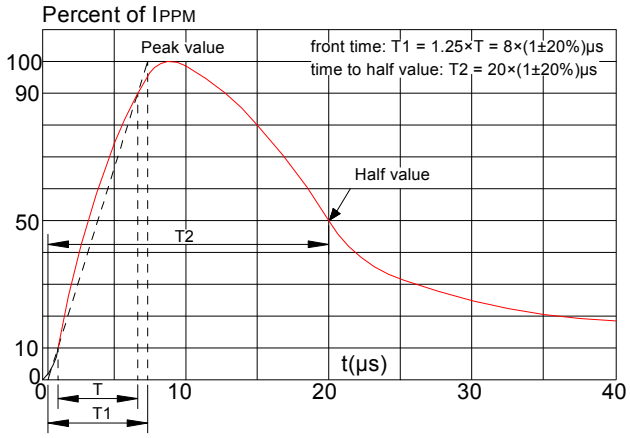


FIG.3: Pulse derating curve

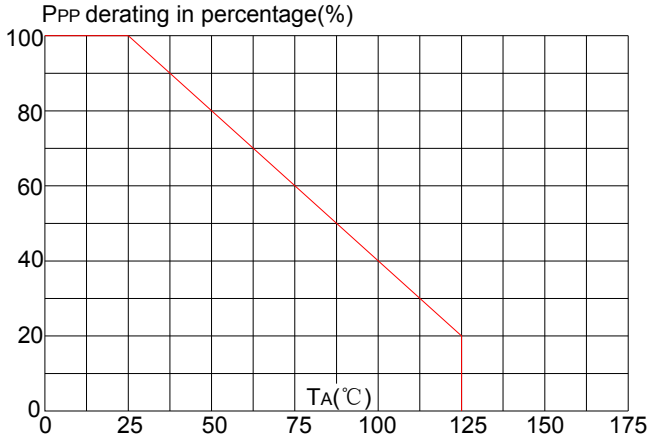
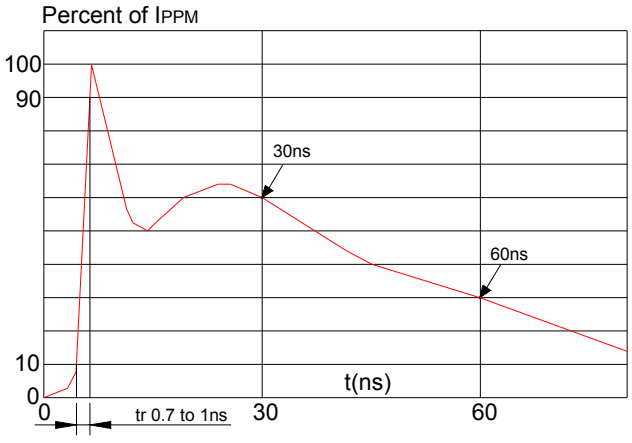
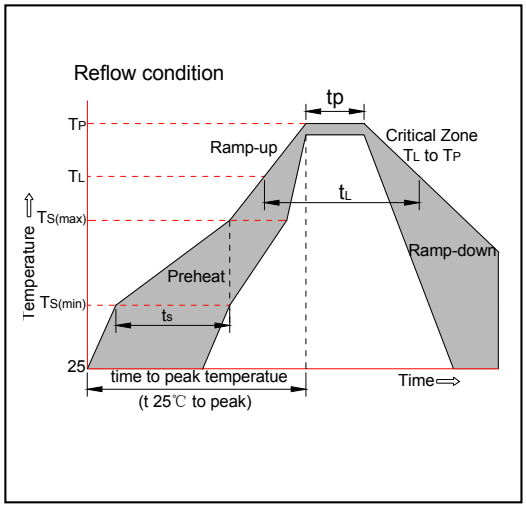


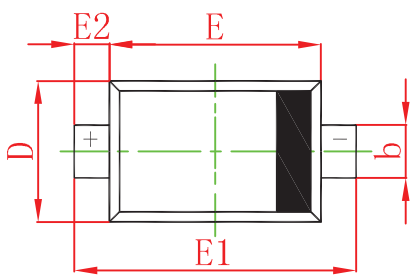
FIG.4: ESD clamping (20kV contact)

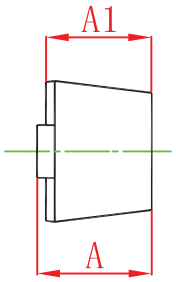


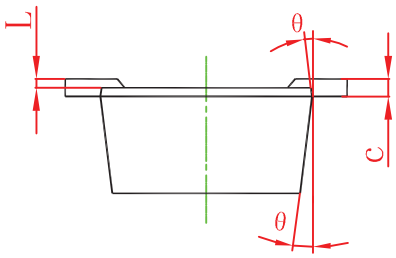
SOLDERING PARAMETERS

Reflow Condition		Pb-Free assembly (see figure at right)
Pre Heat	-Temperature Min ($T_{s(min)}$)	+150℃
	-Temperature Max($T_{s(max)}$)	+200℃
	-Time (Min to Max) (ts)	60-180 secs.
Average ramp up rate (Liquidus Temp (T_L)to peak)		3℃/sec. Max
$T_{s(max)}$ to T_L - Ramp-up Rate		3℃/sec. Max
Reflow	-Temperature(T_L)(Liquidus)	+217℃
	-Temperature(t_L)	60-150 secs.
Peak Temp (T_p)		+260(+0/-5)℃
Time within 5℃of actual Peak Temp (t_p)		20-40secs.
Ramp-down Rate		6℃/sec. Max
Time 25℃ to Peak Temp (T_P)		8 min. Max
Do not exceed		+260℃



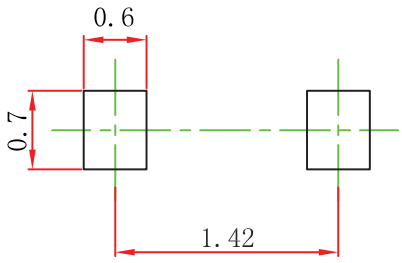






Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A	0.510	0.770	0.020	0.031
A1	0.400	0.700	0.015	0.028
b	0.250	0.350	0.010	0.014
c	0.080	0.150	0.003	0.006
D	0.750	0.850	0.030	0.033
E	1.100	1.300	0.043	0.051
E1	1.500	1.700	0.059	0.067
E2	0.200 REF		0.008 REF	
L	0.010	0.070	0.001	0.003
θ	7° REF		7° REF	

SOD-523 Suggested Pad Layout



Note:
1.Controlling dimension:in millimeters.
2.General tolerance:± 0.05mm.
3.The pad layout is for reference purposes only.